

as inventor, and which is now U.S. Patent No. 6,030,423, which issued February 29, 2000, the disclosure of which is incorporated by reference.--

In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 C.F.R. § 1.121(c)(1)(i).

A marked up version showing amendments to any claims being changed is provided in one or more accompanying pages separate from this amendment in accordance with 37 C.F.R. § 1.121(c)(1)(ii).

1. Canceled.
2. Canceled.
3. Canceled.
4. Canceled.
5. Canceled.
6. Canceled.
7. Canceled.
8. Canceled.

9. (Amended) A method of conductively interconnecting electronic components

comprising:

providing a curable adhesive composition comprising an epoxy terminated silane comprising a glycidoxymethoxy silane;

providing first and second electronic components to be conductively connected with
one another;

CD

interposing the curable adhesive composition between the first and second
electronic components; and

SD

curing the adhesive into an electrically conductive bond electrically interconnecting
the first and second components.

10. The method of claim 9 wherein at least one of the components comprises a
nickel containing metal surface over which the curable adhesive composition is received.

11. ~~Cancel.~~

12. The method of claim 9 wherein the epoxy terminated silane comprises a
glycidoxypolytrimethoxysilane.

13. The method of claim 9 wherein the epoxy terminated silane is present in the
curable adhesive composition at less than or equal to about 2% by weight.

14. The method of claim 9 wherein the epoxy terminated silane is present in the
curable adhesive composition at less than or equal to about 1% by weight.

- 15. Canceled.
- 16. Canceled.
- 17. Canceled.
- 18. Canceled.
- 19. Canceled.
- 20. Canceled.
- 21. Canceled.
- 22. Canceled.

23. A method of conductively interconnecting electronic components comprising: interposing a curable epoxy composition between first and second electrically conductive components to be electrically interconnected, at least one of the components comprising a metal surface with which the curable epoxy is to electrically connect; and curing the epoxy into an electrically conductive bond electrically interconnecting the first and second components, the epoxy having an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a contact resistance through said metal surface of less than or equal to about 0.3 ohm-cm².

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24. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.16 ohm- cm².

25. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.032 ohm- cm².

26. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 2% by weight.

27. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 1% by weight.

28. The method of claim 23 wherein the metal surface comprises nickel over which the curable adhesive composition is received.

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- 29. Canceled.
- 30. Canceled.
- 31. Canceled.
- 32. Canceled.
- 33. Canceled.
- 34. Canceled.
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- 40. Canceled.
- 41. Canceled.
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- 48. Canceled.
- 49. Canceled.
- 50. Canceled.